

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	99	mask same (insulating or insulator) and (droplet with discharge) and planarization and (gate with insulating)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/25 11:38
S2	50	mask same (insulating or insulator) and ((droplet with discharge) same wiring) and planarization and (gate with insulating)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/25 11:39
S3	1	"10/554113"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/25 13:56
S4	9	("20020053881"   "20020136829"   "5084905"   "6416583"   "6426595"   "6627263").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/25 14:12
S5	3	("20020053881"   "20020136829"   "5084905"   "6416583"   "6426595"   "6627263").PN. and (drop or jet or droplet)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/25 14:13
S6	0	"WO 02/067335 A1"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/26 13:59

S7	1	"WO 02067335 A1"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/26 13:59
S8	2	"6952036".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/26 14:00
S9	82	(electroless adj plating) with (drop or droplet)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/26 15:38
S10	0	(electroless adj plating) with (by adj (drop or droplet))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/26 15:40
S11	40	(electroless adj plating) with (droplet)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/26 15:41
S12	1	"10/579443"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/28 12:02
S13	4404	(first adj solvent) with (second adj solvent)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/28 12:09

S14	21	(first adj solvent) with (second adj solvent) same mask	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/28 12:10
S15	11	(first adj solvent) with (second adj solvent) same mask and (nozzle or discharge or drop or droplet)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/28 12:10
S16	19	planarization same heat same press	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/28 12:33
S17	16867	(257/57,59,66,72,776.ccls. 438/149,151,157,166,128,48,283,280,619.ccls.)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/28 12:58
S18	99	mask same (insulating or insulator) and (droplet with discharge) and planarization and (gate with insulating)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/28 12:58
S19	20	S17 and S18	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/28 12:58
S20	2	"20010029066".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/08 10:47

S21	62351	(nozzle) with first with second	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/08 14:25
S22	101	mask same (insulating or insulator) and (droplet with discharge) and planarization and (gate with insulating)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/08 14:25
S23	3	S21 and S22	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/08 14:25
S24	8491	(nozzle with plurality) with first with second	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/08 14:27
S25	105	mask and (insulating or insulator) and (droplet with discharge) and planarization and (gate with insulating)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/08 14:28
S26	2	S24 and S25	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/08 14:28
S27	380	(nozzle with plurality) with mask	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/08 14:28

S28	1	S27 and S22	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/08 14:29
S29	16913	(257/57,59,66,72,776.ccls. 438/149,151,157,166,128,48,283,280,619.ccls.)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/08 14:29
S30	3	S27 and S29	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/08 14:29
S31	4	mask same (insulating or insulator) and ((droplet with discharge) same wiring) and planarization and (gate with insulating) and @pd> "20081126"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/03/25 23:37
S32	3	(electroless adj plating) with (droplet) and @pd> "20081126"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/03/25 23:38
S33	0	(first adj solvent) with (second adj solvent) same mask and (nozzle or discharge or drop or droplet) and @pd> "20081126"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/03/25 23:38
S34	406	(nozzle with plurality) with mask	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/03/25 23:38

S35	17427	(257/57,59,66,72,776.ccls. 438/149,151,157,166,128,48,283,280,619.ccls.)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/03/25 23:38
S36	3	S34 and S35	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/03/25 23:38
S37	0	(method and base and layer and insulating and mask and depression and etching and emedded and wiring and planarization and upper and surface).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/03/25 23:40

3/25/09 11:40:50 PM

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